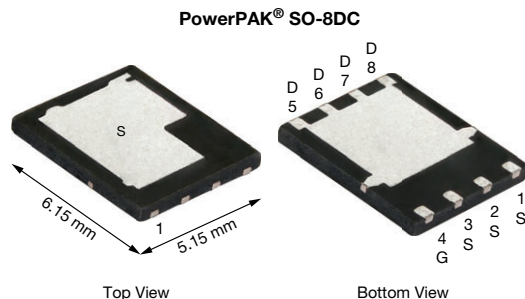


N-Channel 30 V (D-S) MOSFET



FEATURES

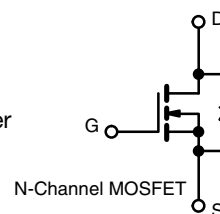
- TrenchFET® Gen IV power MOSFET
- Optimized Q_g , Q_{gd} , and Q_{gd}/Q_{gs} ratio reduces switching related power loss
- Top side cooling feature provides additional venue for thermal transfer
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Synchronous rectification
- High power density DC/DC
- Synchronous buck converter
- OR-ing
- Load switching
- Battery management



PRODUCT SUMMARY	
V_{DS} (V)	30
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.00080
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5$ V	0.00115
Q_g typ. (nC)	48
I_D (A)	100 ^{a, g}
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK SO-8DC
Lead (Pb)-free and halogen-free	SiDR390DP-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	30	V	
Gate-source voltage	V_{GS}	+20 / -16		
Continuous drain current ($T_J = 150$ °C)	$T_C = 25$ °C	100 ^a	A	
	$T_C = 70$ °C	100 ^a		
	$T_A = 25$ °C	69.9 ^{b, c}		
	$T_A = 70$ °C	55.9 ^{b, c}		
Pulsed drain current ($t = 100$ μ s)	I_{DM}	400		
Continuous source-drain diode current	$T_C = 25$ °C	100		
	$T_A = 25$ °C	5.6 ^{b, c}		
Single pulse avalanche current	$L = 0.1$ mH	40		
Single pulse avalanche energy	E_{AS}	80	mJ	
Maximum power dissipation	$T_C = 25$ °C	125	W	
	$T_C = 70$ °C	80		
	$T_A = 25$ °C	6.25 ^{b, c}		
	$T_A = 70$ °C	4 ^{b, c}		
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150		
Soldering recommendations (peak temperature) ^c		260		°C

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	$t \leq 10$ s	R_{thJA}	15	20
Maximum junction-to-case (drain)	Steady state	R_{thJC}	0.8	1
Maximum junction-to-case (source)	Steady state	R_{thJC}	1.1	1.4

Notes

- Package limited
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 54 °C/W
- $T_C = 25$ °C

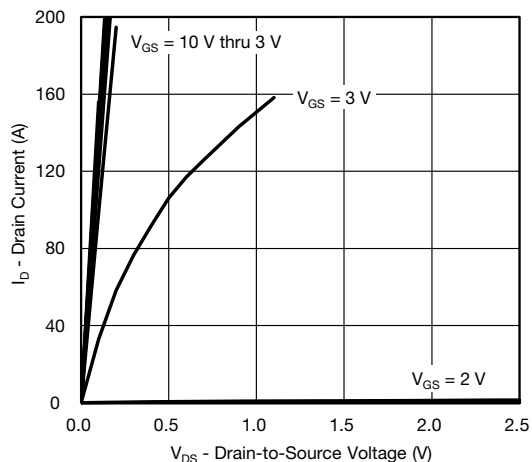
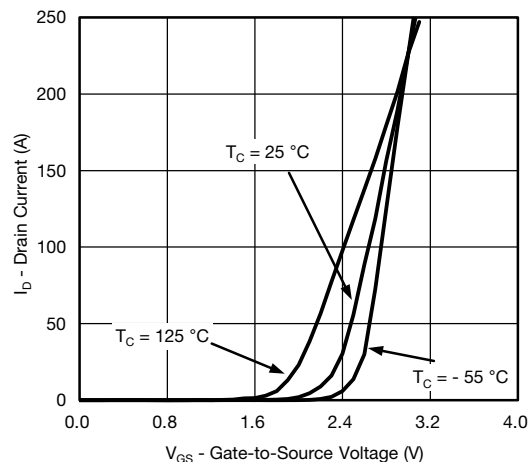
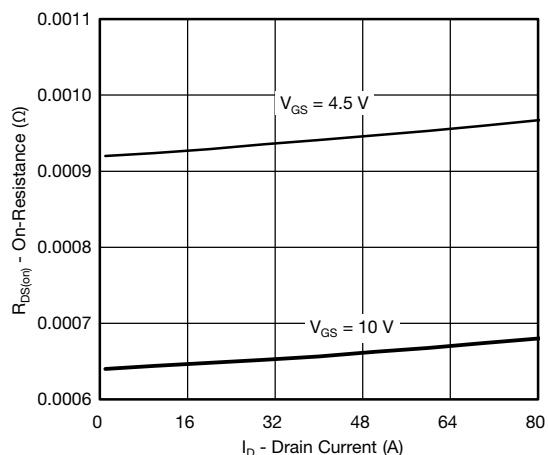
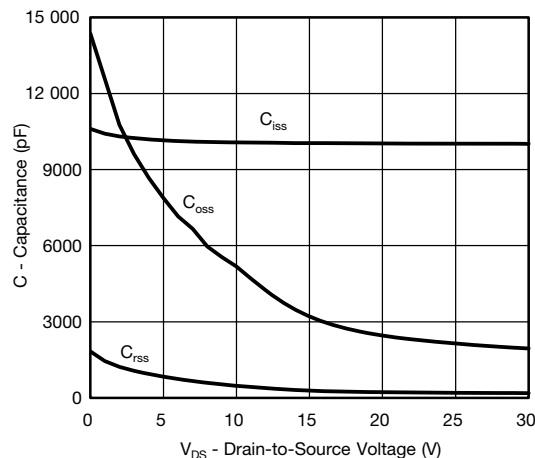
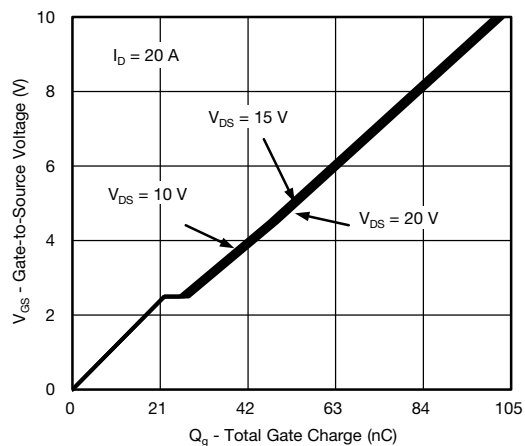
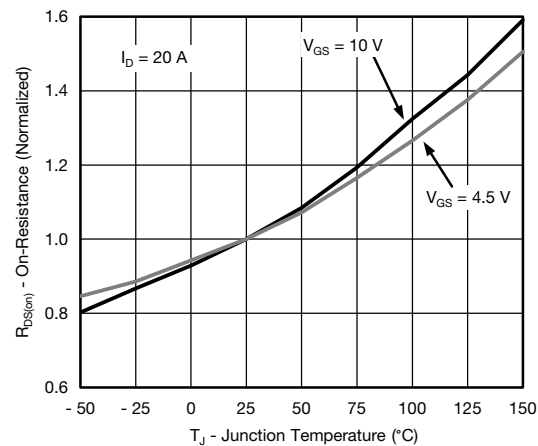


SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	-	17.5	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	-6.3	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.8	-	2	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20, -16 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	
On-state drain current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	50	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A	-	0.00065	0.00080	Ω
		V _{GS} = 4.5 V, I _D = 15 A	-	0.00090	0.00115	
Forward transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 20 A	-	110	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	-	10 180	-	pF
Output capacitance	C _{oss}		-	3290	-	
Reverse transfer capacitance	C _{rss}		-	306	-	
C _{rss} /C _{iss} ratio			-	0.031	0.062	
Total gate charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A	-	102	153	nC
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A	-	48	72	
Q _{gs}	-		22	-		
Q _{gd}	-		4.7	-		
Output charge	Q _{oss}	V _{DS} = 15 V, V _{GS} = 0 V	-	105	-	
Gate resistance	R _g	f = 1 MHz	0.5	1.3	2.5	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = 15 V, R _L = 0.75 Ω I _D ≅ 20 A, V _{GEN} = 10 V, R _g = 1 Ω	-	15	30	ns
Rise time	t _r		-	16	32	
Turn-off delay time	t _{d(off)}		-	46	90	
Fall time	t _f		-	10	20	
Turn-on delay time	t _{d(on)}	V _{DD} = 15 V, R _L = 0.75 Ω I _D ≅ 20 A, V _{GEN} = 4.5 V, R _g = 1 Ω	-	51	100	
Rise time	t _r		-	63	120	
Turn-off delay time	t _{d(off)}		-	78	155	
Fall time	t _f		-	27	34	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	100	A
Pulse diode forward current (t _p = 100 μs)	I _{SM}		-	-	400	
Body diode voltage	V _{SD}	I _S = 10 A	-	0.68	1.1	V
Body diode reverse recovery time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C	-	68	135	ns
Body diode reverse recovery charge	Q _{rr}		-	98	180	nC
Reverse recovery fall time	t _a		-	29	-	ns
Reverse recovery rise time	t _b		-	39	-	

Notes

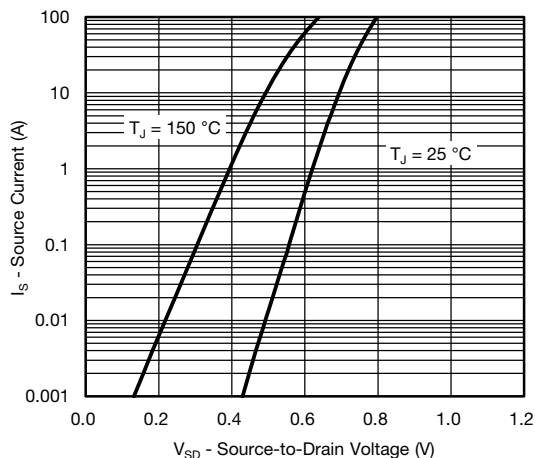
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

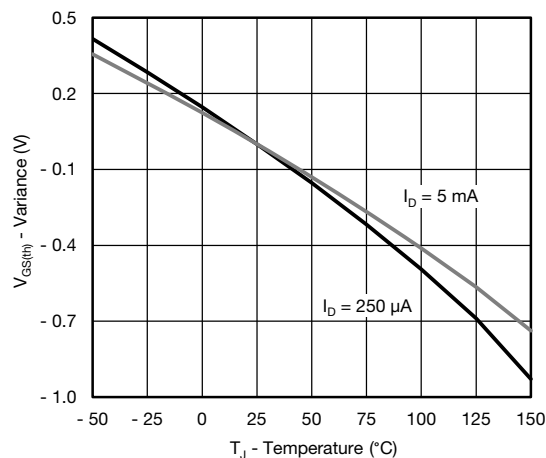
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



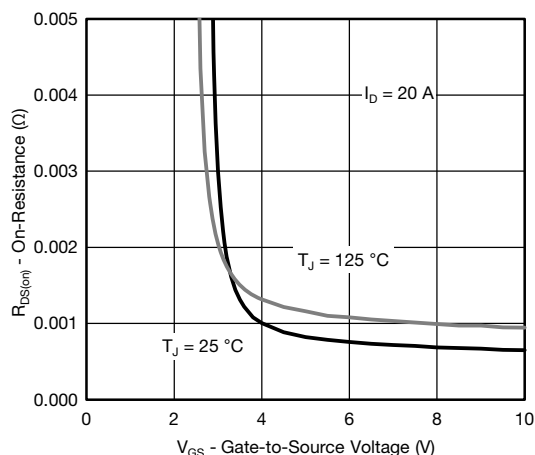
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



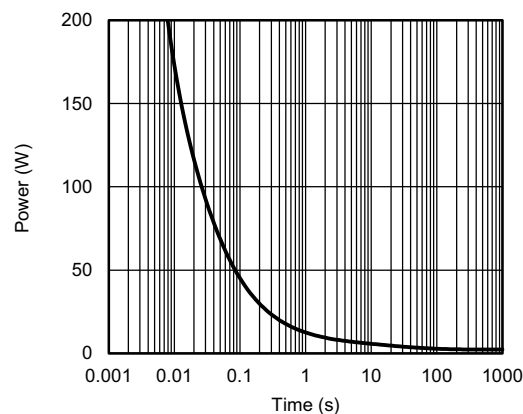
Source-Drain Diode Forward Voltage



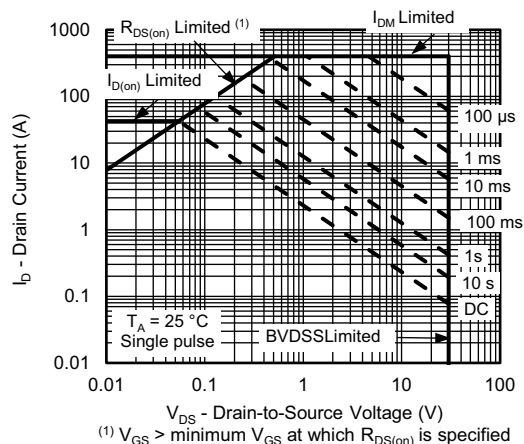
Threshold Voltage



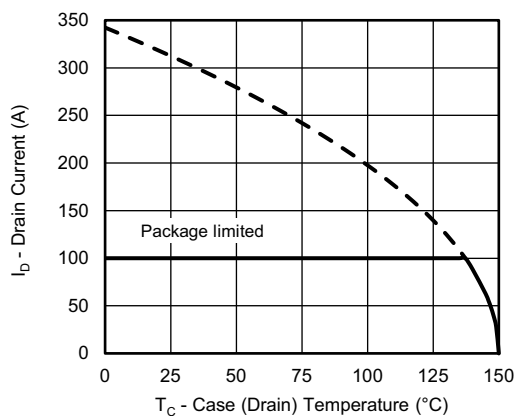
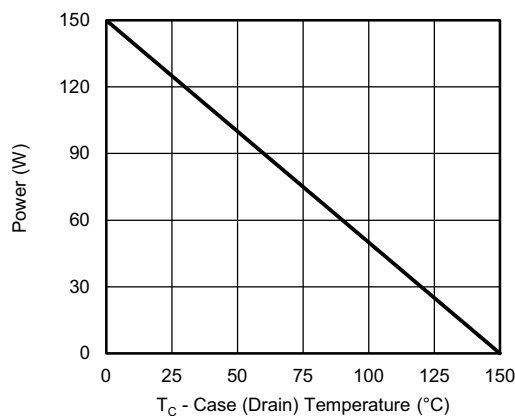
On-Resistance vs. Gate-to-Source Voltage



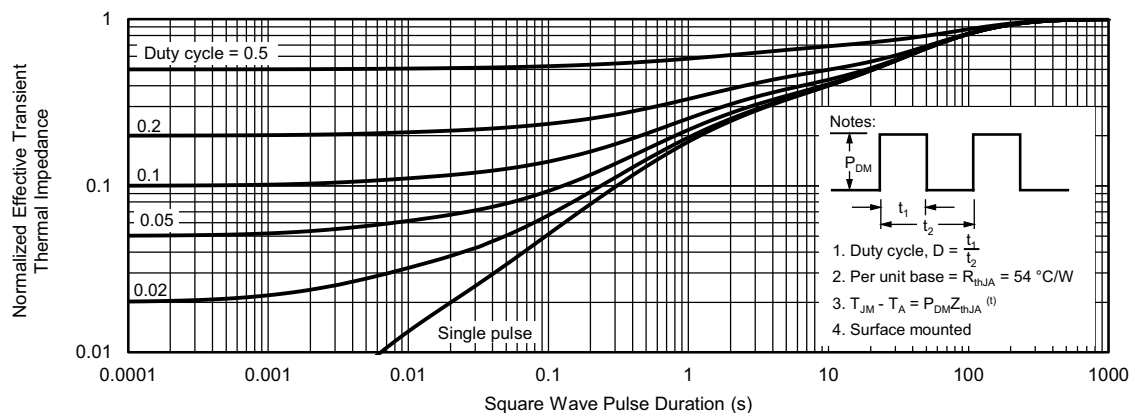
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

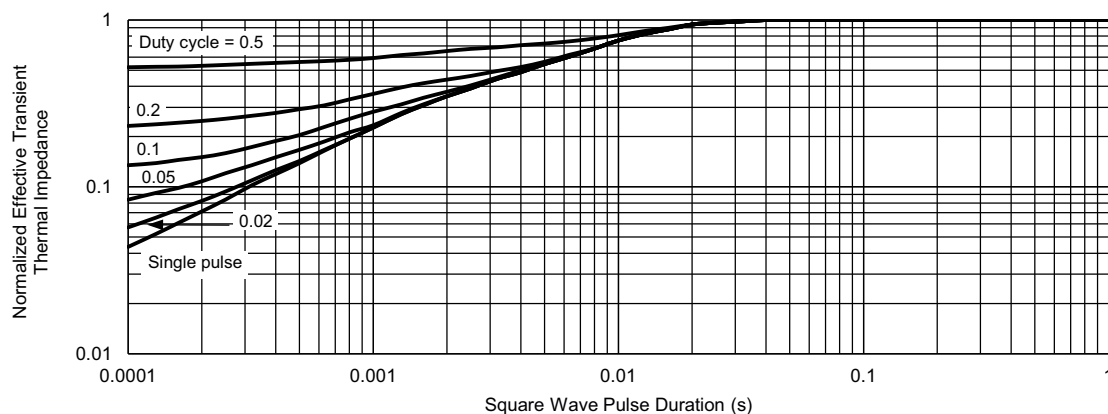
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case
Note

- a. The power dissipation P_D is based on $T_J \text{ max.} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

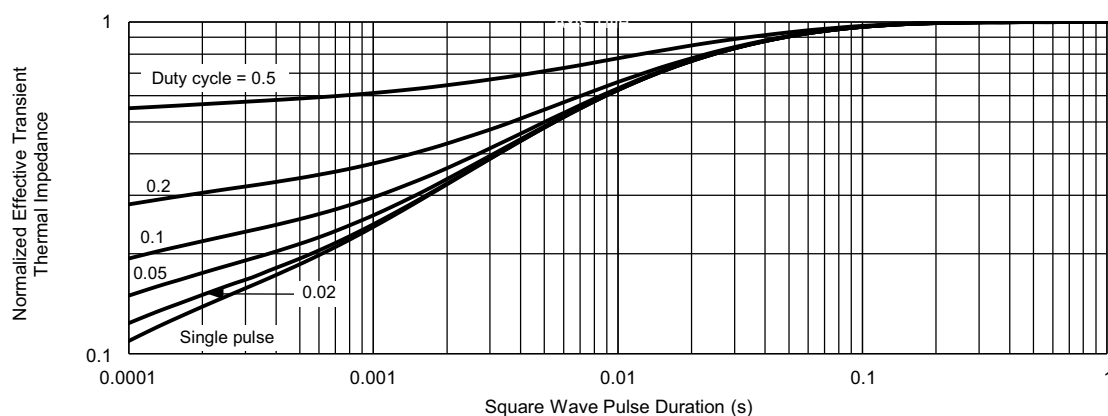

Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case (Drain)

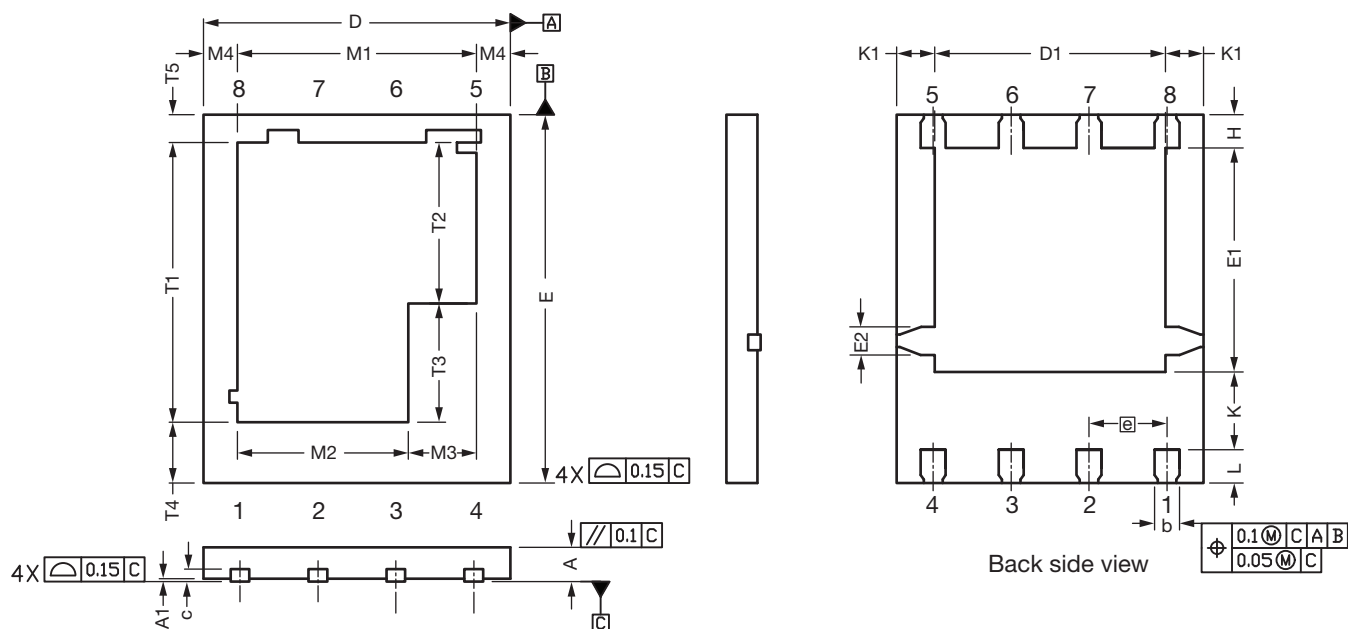


Normalized Thermal Transient Impedance, Junction-to-Case (Source)

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75636.

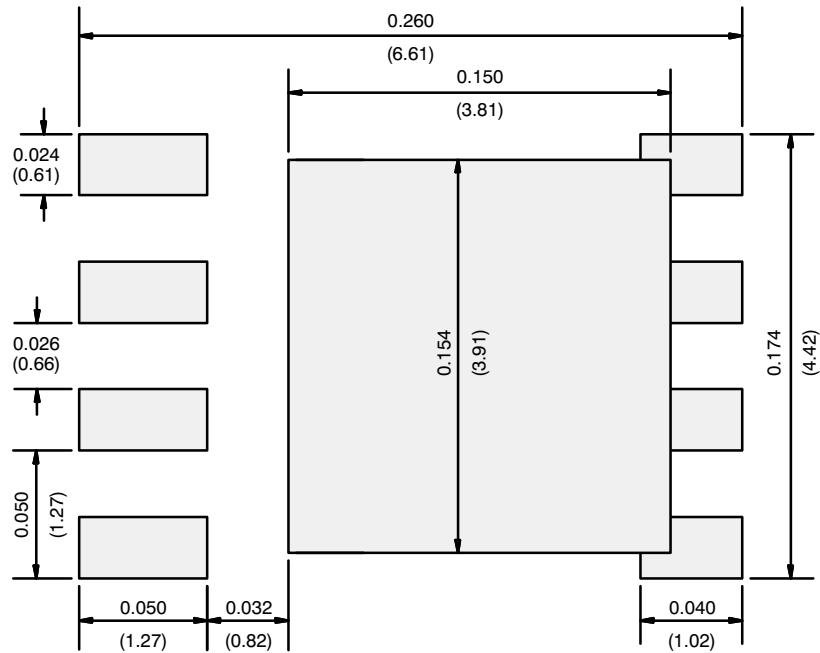


PowerPAK® SO-8 Double Cooling Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.51	0.56	0.61	0.020	0.022	0.024
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.36	0.41	0.46	0.014	0.016	0.018
c	0.15	0.20	0.25	0.006	0.008	0.010
D	4.90	5.00	5.10	0.193	0.197	0.201
D1	3.71	3.76	3.81	0.146	0.148	0.150
e	1.27 BSC			0.050 BSC		
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	3.60	3.65	3.70	0.142	0.144	0.146
E2	0.46 typ.			0.018 typ.		
H	0.49	0.54	0.59	0.019	0.021	0.023
K	1.22	1.27	1.32	0.048	0.050	0.052
K1	0.64 typ.			0.025 typ.		
L	0.49	0.54	0.59	0.019	0.021	0.023
M1	3.8	3.90	4.00	0.150	0.154	0.158
M2	2.69	2.79	2.89	0.106	0.110	0.114
M3	1.01	1.11	1.21	0.040	0.044	0.048
M4	0.56 typ.			0.022 typ.		
N	8			8		
T1	4.46	4.56	4.66	0.176	0.180	0.184
T2	2.53	2.63	2.73	0.100	0.104	0.108
T3	1.83	1.93	2.03	0.072	0.076	0.080
T4	0.97 typ.			0.038 typ.		
T5	0.48 typ.			0.019 typ.		
ECN: T24-0304-Rev. C, 29-Jul-2024						
DWG: 6048						

RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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